



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Ming-Yi LAY, et al.

Serial No.: 09/764,207

Filed: January 19, 2001

For: METAL BUMP WITH AN INSULATING SIDEWALL AND METHOD OF
FABRICATING THEREOF

Confirmation No.: 7484

Examiner: M. Wilczewski

Art Unit: 2822

Docket No.: H010011

*Election
#6
9/9/03*

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RESPONSE TO THE RESTRICTION REQUIREMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

August 29, 2003

Sir:

In response to the Restriction Requirement dated June 6, 2003, with the period for response being due on September 6, 2003, Applicants hereby elect to prosecute Group I Claims 1-10 (drawn to a structure comprising a plurality of metal bumps for connecting a non-conducting substrate and a chip, classified in class 257, subclass 678+) without traverse. Applicants reserve the right to file a divisional application directed to non-elected claims.

If any additional fees are due with regard to this paper, please charge counsel's Deposit Account No. 50-2394.

Respectfully submitted,

IPS, Inc.

Robert J. Forsell, Jr.

Robert J. Forsell, Jr.
Reg. No. 51,693

*election
w/o traverse*

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